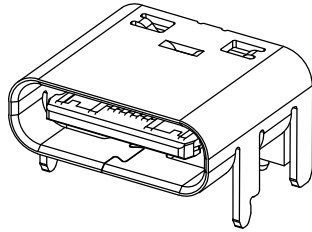
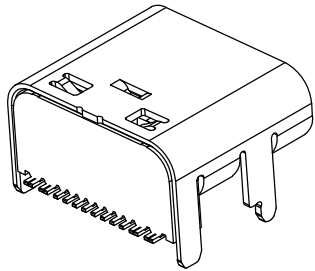
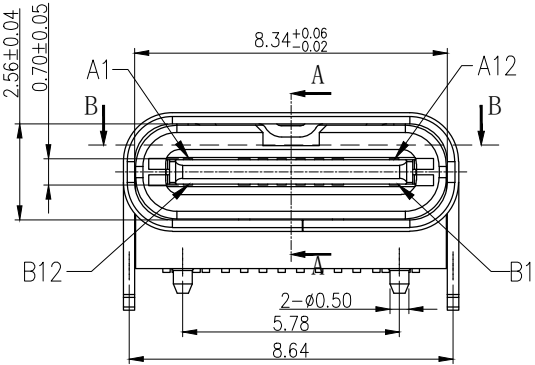


标 记 MARK	ECN编号/变更内容 ECN NO/DEFINITION	修 改 REVISE	日 期 DATE	核 准 APPROVE

PIN NUMBER	SIGNAL NAME	PIN NUMBER	SIGNAL NAME
A1	GND	B12	GND
A4	VBUS	B9	VBUS
A5	CC1	B8	SBU2
A6	Dp1	B7	Dn2
A7	Dn1	B6	Dp2
A8	SBU1	B5	CC2
A9	VBUS	B4	VBUS
A12	GND	B1	GND



NOTE:

1.MATERIAL SPECIFICATION:

1.HOUSING:HIGH TEMPERATURE RESISTANT PLASTIC,

2.CONTACTS:COPPER ALLOY

3.MID PLATE: STAINLESS STEEL

2.PLATING SPECIFICATION:

2-1.CONTACTS:

Ni 50u" MIN. UNDER PLATED OVER ALL.

Au PLATED ON THE FUNCTIONAL AREA OF CONTACT.

(GOLD PLATING THICKNESS FOLLOW THE P/N)

GOLD FLASH PLATING ON SOLDER AREA

2-2.FRONT SHELL:

Ni 30u" MIN. UNDER PLATED OVER ALL.

3.MECHANICAL PERFORMANCE,

3-1.INSERTION FORCE: 0.5~2.0kgf.

3-2.REMOVAL FORCE: 0.8kgf~2.0kgf.

3-3.DURABILITY: 10000 CYCLES.

4.ELECTRICAL PERFORMANCE,

4-1. CURRENT RATING:5A

VOLTAGE RATING: 20V

4-2.INSULATION RESISTANCE: 100MΩ MIN

4-3.DIELECTRIC WITHSTAND VOLTAGE,AC 100V FOR 1 MINUTE.

4-4.LOW CONTACT RESISTANCE: INITIAL 40MΩ

AFTER 50MΩ

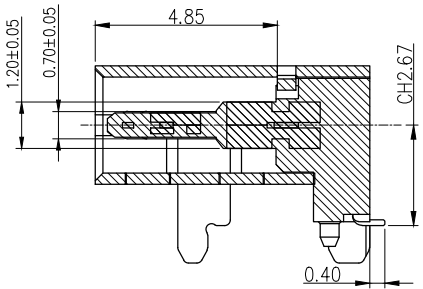
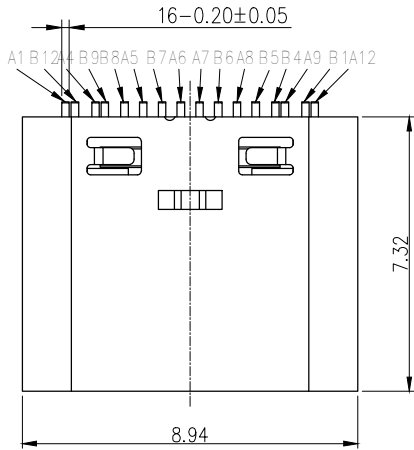
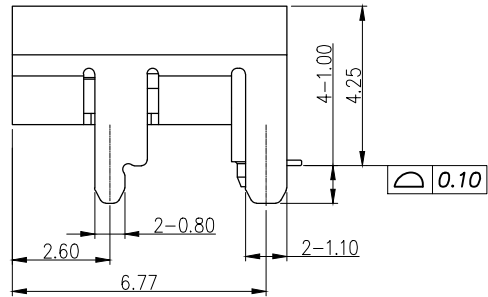
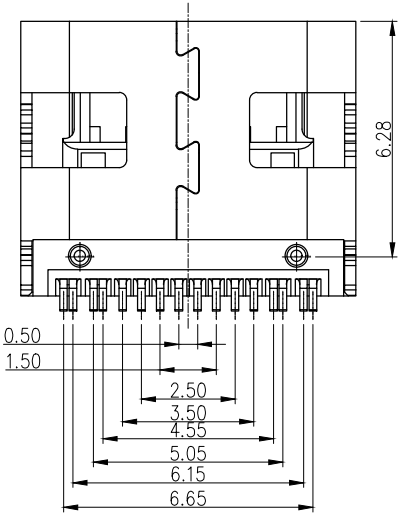
5. ENVIRONMENTAL PERFORMANCE:

OPERATING TEMPERATURE: -30℃~+80℃.

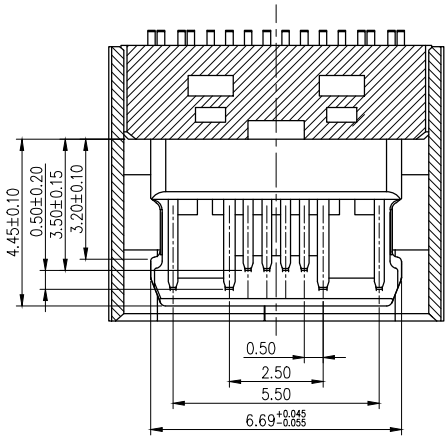
6.IR REFLOW:

THE PEAK TEMPERATURE ON THE BOARD SHALL

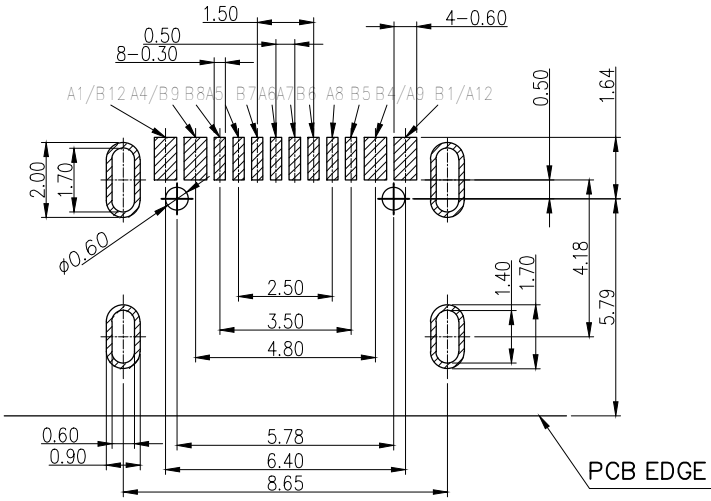
BE MAINTAINED FOR 10 SECONDS AT 260℃.



SECTION A-A
SCALE 1:1



SECTION B-B
SCALE 1:1



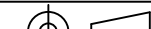
RECOMMEND P.C.B LAYOUT (COMPONENT SIDE)
TOLERANCE FOR PCB LAYOUT IS ± 0.05

3	外壳	不锈钢	镀镍	
2	接触	铜	镀金	
1	基座	LCP	黑色	
序 号	品 名	材 质	电镀/颜色	备 注



深圳市虹成电子有限公司

品 名 TITLE	TYPE-C母座
料 号 PART NO	HC-TYPE-C-16P-G031B

GENERAL TOLERANCES (UNLESS SPECIFIED)		比 列 SCALE	1:1			
.0	±0.35	单 位 UNIT	MM	制 图 DRAW	AhYe	
.00	±0.25	张 数 PART NO	1 OF 1	审 核 CHECKED	夏操云	
.000	±0.15					
X. °	±2.00°	版 本 REV	A	批 准 APPROVE	赵亮亮	